## **AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

- 1.-52. Canceled.
- 53. (New) A nitride semiconductor device having a nitride semiconductor layer structure comprising:

an active layer of a quantum well structure which has a first surface and a second surface and which comprises an indium-containing nitride semiconductor;

a first nitride semiconductor layer which is formed to adjoin the first surface of the active layer and has a band gap energy larger than that of the active layer;

a second nitride semiconductor layer which is formed on the first surface side of the active layer at a location more distant from the active layer relative to the first nitride semiconductor layer, which has a band gap energy smaller than that of the first nitride semiconductor layer and which has a thickness larger that that of the first nitride semiconductor layer; and

a third nitride semiconductor layer which is formed on the first surface side of the active layer at a location more distant from the active layer relative to the second nitride semiconductor layer and which has a band gap energy larger than that of the second nitride semiconductor layer.

54. (New) The device according to claim 53, wherein me first nitride semiconductor layer has a thickness 0110 angstroms to 0.1 μm.

- 55. (New) The device according to claim 53, wherein the active layer is doped with an impurity.
- 56. (New) The device according to Claim 53, wherein the layer structure is provided on a p-side of the active layer.
- 57. (New) The device according to Claim 56, wherein the second nitride semiconductor layer adjoins the first nitride semiconductor layer.
- 58. (New) The device according to Claim 56, which is a laser device, wherein the second nitride semiconductor layer is a light guiding layer, and the nitride semiconductor layer is a light confinement layer.
- 59. (New) The device according to Claim 53, wherein the layer structure is provided on an n-side of the active layer.
- 60. (New) The device according to Claim 59, wherein the second nitride semiconductor layer adjoins the first nitride semiconductor layer.
- 61. (New) The device according to Claim 60, which is a laser device, wherein the second nitride semiconductor layer is a light guiding layer, and the nitride semiconductor layer is a light confinement layer.
- 62. (New) The device according to claim 53, wherein the second nitride semiconductor layer comprises an indium-containing nitride semiconductor or GaN.
- 63. (New) The device according to claim 62, wherein the third nitride semiconductor layer comprises an aluminum-containing nitride semiconductor.
  - 64. (New) The device according to claim 53, wherein the layer structure is

provided on an n-side of the active layer, and a contact layer is provided at a location more distant from the active layer relative to the third layer.

- 65. (New) The device according to claim 64, further comprising an indiumcontaining nitride semiconductor layer between the contact layer and the third nitride semiconductor layer.
- 66. (New) The device according to claim 53, wherein the second nitride semiconductor layer comprises an indium-containing nitride semiconductor.
  - 67. (New) A nitride semiconductor device comprising:

a first clad layer comprising an n-type nitride semiconductor;

an active layer of a quantum well structure provided on the first clad layer, the active layer comprising a nitride semiconductor containing indium and gallium and having at least one well layer having a thickness not greater than 70 angstroms, wherein the well layer is placed on an underlying layer in a state lattice-mismatched with the underlying layer and includes a plurality of indium-rich regions and indium poor regions; and

a second clad layer which is provided on the active layer and comprises a nitride semiconductor doped with an acceptor impurity.

- 68. (New) The device according to claim 67, wherein the active layer is doped with an impurity.
- 69. (New) The device according to claim 68, wherein the impurity comprises silicon or germanium.

- 70. (New) The device according to claim 68, wherein the impurity is doped in the well layer.
- 71. (New) A nitride semiconductor device including a first n-type layer which comprises an n-type, aluminum-containing nitride semiconductor or n-type gallium nitride; and a second n-type layer which comprises an n-type, aluminum-containing nitride semiconductor, wherein the device has a third n-type layer which comprises an n-type, indium-containing nitride semiconductor between the first n-type layer and the second n-type layer.
- 72. (New) A light-emitting nitride semiconductor device having a nitride semiconductor layer structure and a single light-emitting layer, the device comprising:

an active layer of a quantum well structure which has a first surface and a second surface and which comprises an indium-containing nitride semiconductor;

a first nitride semiconductor layer which is formed to adjoin the first surface of the active layer and has a band gap energy larger than that of the active layer;

a second nitride semiconductor layer which is a light guiding layer and is formed on the first surface side of the active layer at a location more distant from the active layer relative to the first nitride semiconductor layer and which has a band gap energy smaller than that of the first nitride semiconductor layer; and

a third nitride semiconductor layer which is formed on the first surface side of the active layer at a location more distant from the active layer relative to the second nitride semiconductor layer and which has a band gap energy larger than that of the second

nitride semiconductor layer.

- 73. (New) A method of producing a nitride semiconductor device having an active layer of quantum well structure including a well layer comprising an indium-containing nitride semiconductor, the method comprising growing an indium containing nitride semiconductor as the well layer: and allowing the grown well layer to stand until indium-rich and indium poor regions are formed in the surface of the well layer.
- 74. (New) The method according to claim 73, wherein the well layer is formed above an underlying layer which is lattice-mismatched with the well layer.
- 75. (New) The method according to claim 74, wherein the well layer comprises  $ln_fGa_{1-f}N$  where 0 < f < 1, and the underlying layer comprises  $ln_fGa_{1-f}N$  where 0 < f < 1, and f' < f.